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**Yilmaz et al.**

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(54) **STACKED DUAL CHIP PACKAGE HAVING LEVELING PROJECTIONS**

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**Related U.S. Application Data**

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**H01L 23/02** (2006.01)  
**H01L 23/00** (2006.01)  
**H01L 23/31** (2006.01)

(52) **U.S. Cl.**  
CPC .... **H01L 23/49541** (2013.01); **H01L 23/49524** (2013.01); **H01L 23/49537** (2013.01); **H01L**

**23/49562** (2013.01); **H01L 23/49575** (2013.01); **H01L 24/37** (2013.01); **H01L 24/40** (2013.01); **H01L 24/41** (2013.01); **H01L 24/81** (2013.01); **H01L 24/84** (2013.01); **H01L 23/3107** (2013.01); **H01L 24/48** (2013.01); **H01L 2224/27013** (2013.01); **H01L 2224/2929** (2013.01); **H01L 2224/29101** (2013.01); **H01L 2224/32245** (2013.01); **H01L 2224/37011** (2013.01); **H01L 2224/40247** (2013.01); **H01L 2224/48247** (2013.01); **H01L 2224/92** (2013.01); **H01L 2924/014** (2013.01); **H01L 2924/01006** (2013.01); **H01L 2924/01013** (2013.01); **H01L 2924/01029** (2013.01); **H01L 2924/01033** (2013.01); **H01L 2924/01067** (2013.01); **H01L 2924/01079** (2013.01); **H01L 2924/01082** (2013.01); **H01L 2924/1306** (2013.01); **H01L 2924/13091** (2013.01); **H01L 2924/14** (2013.01)

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USPC ..... **257/666**, **672**, **675**, **676**, **685**, **686**, **692**, **257/693**, **698**, **723**, **724**, **734**, **777**, **E23.042**, **257/E23.043**, **E23.046**, **E23.052**, **E23.061**  
See application file for complete search history.

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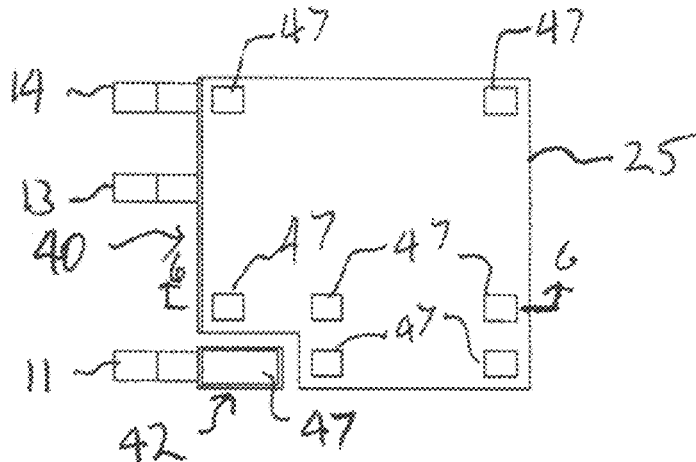
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(57) **ABSTRACT**

The present invention is directed to a lead-frame having a stack of semiconductor dies with interposed metalized clip structure. Level projections extend from the clip structure to ensure that the clip structure remains level during fabrication.

**16 Claims, 17 Drawing Sheets**



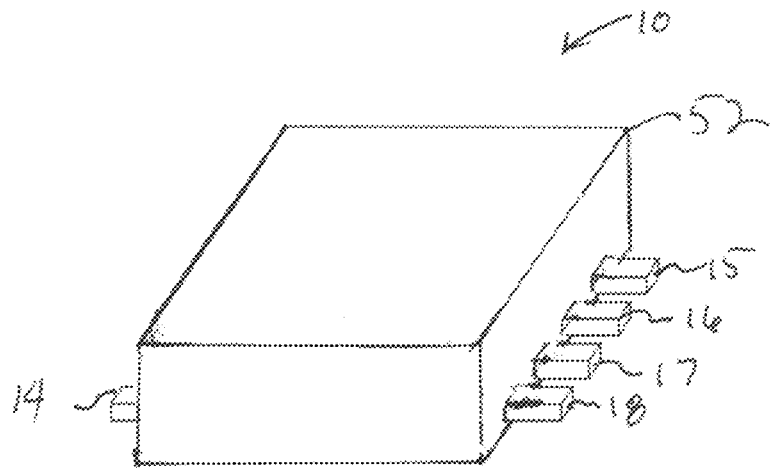


FIG. 1

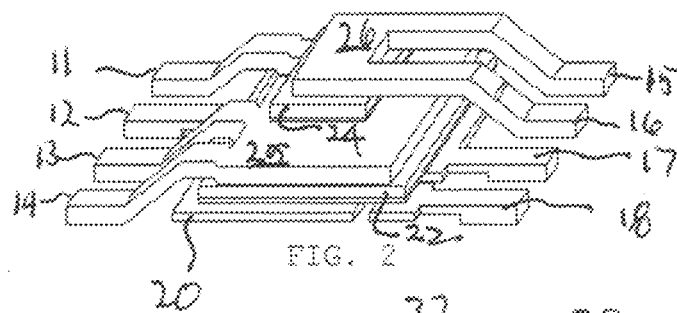


FIG. 2

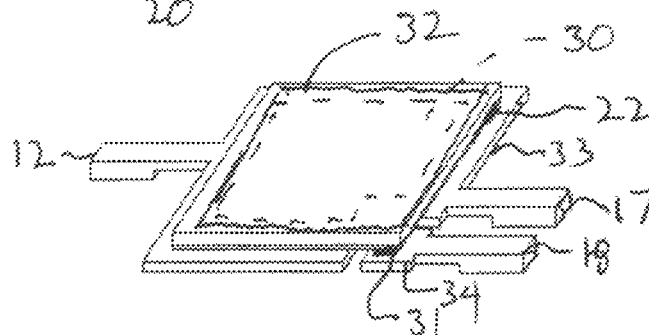


FIG. 3

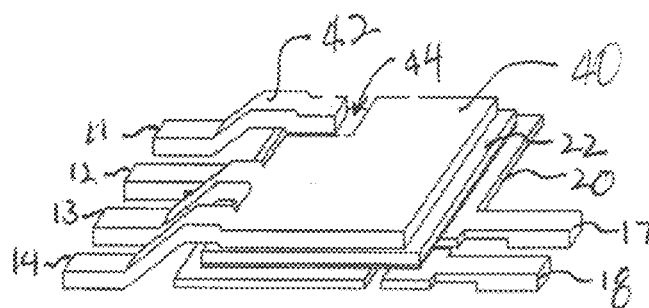


FIG. 4

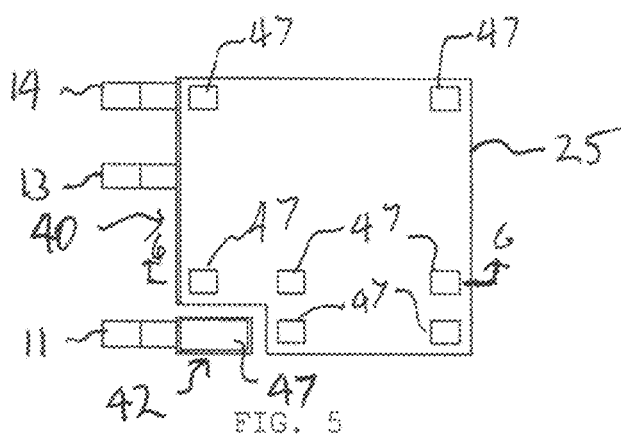


FIG. 5

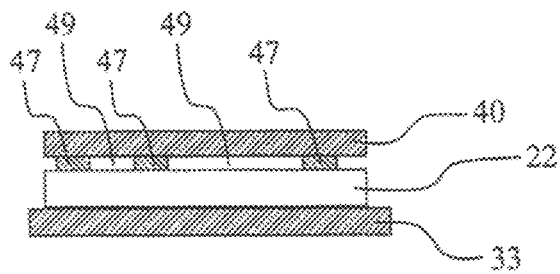


Fig. 6

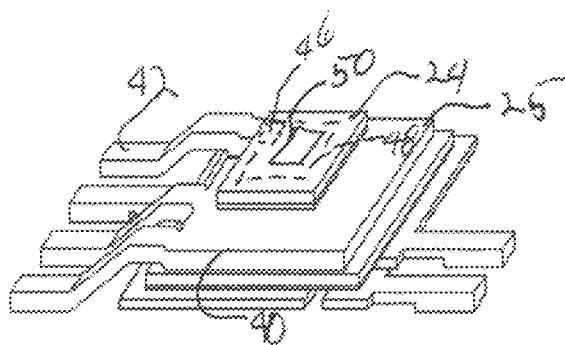


FIG. 7

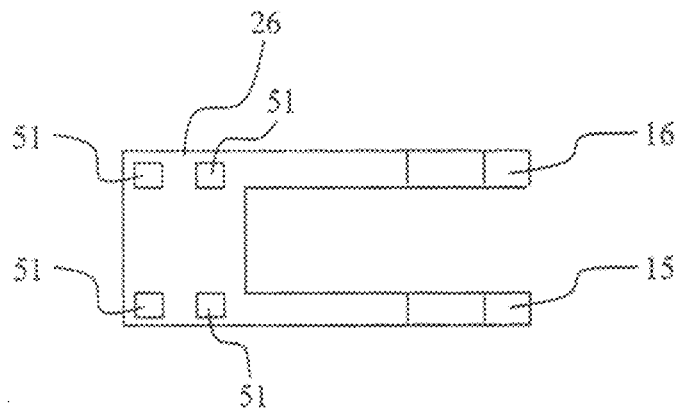


Fig. 8

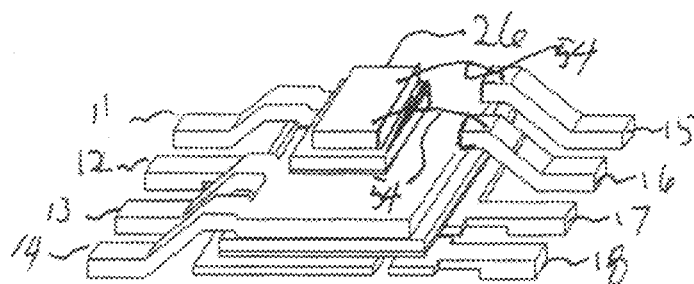


FIG. 9

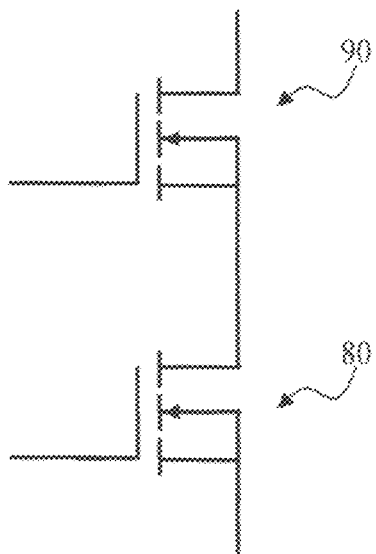


Fig. 10A

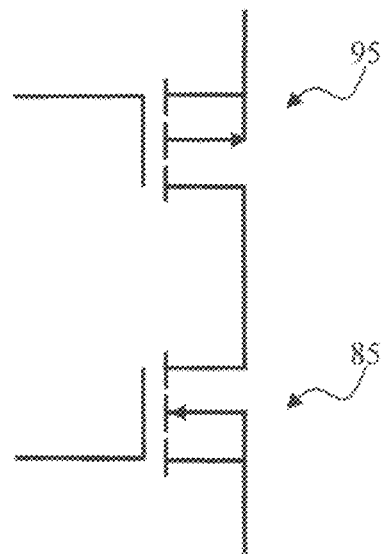


Fig. 10B

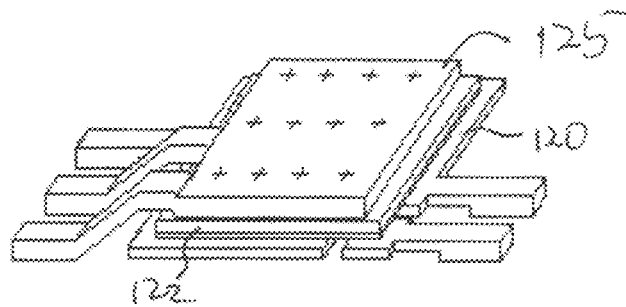


FIG. 11

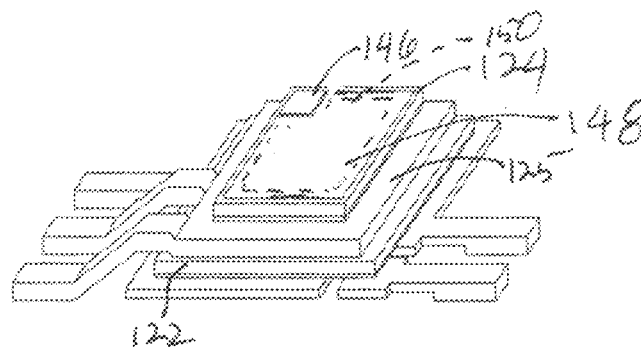


FIG. 12

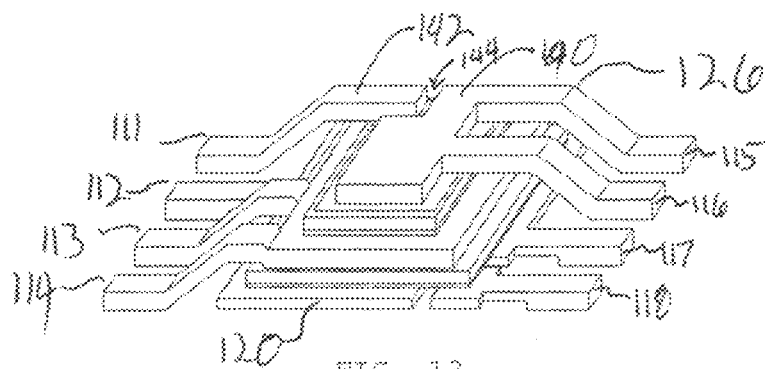


FIG. 13

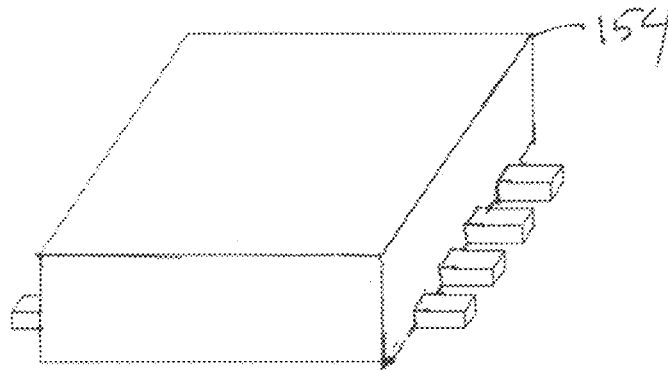


FIG. 14



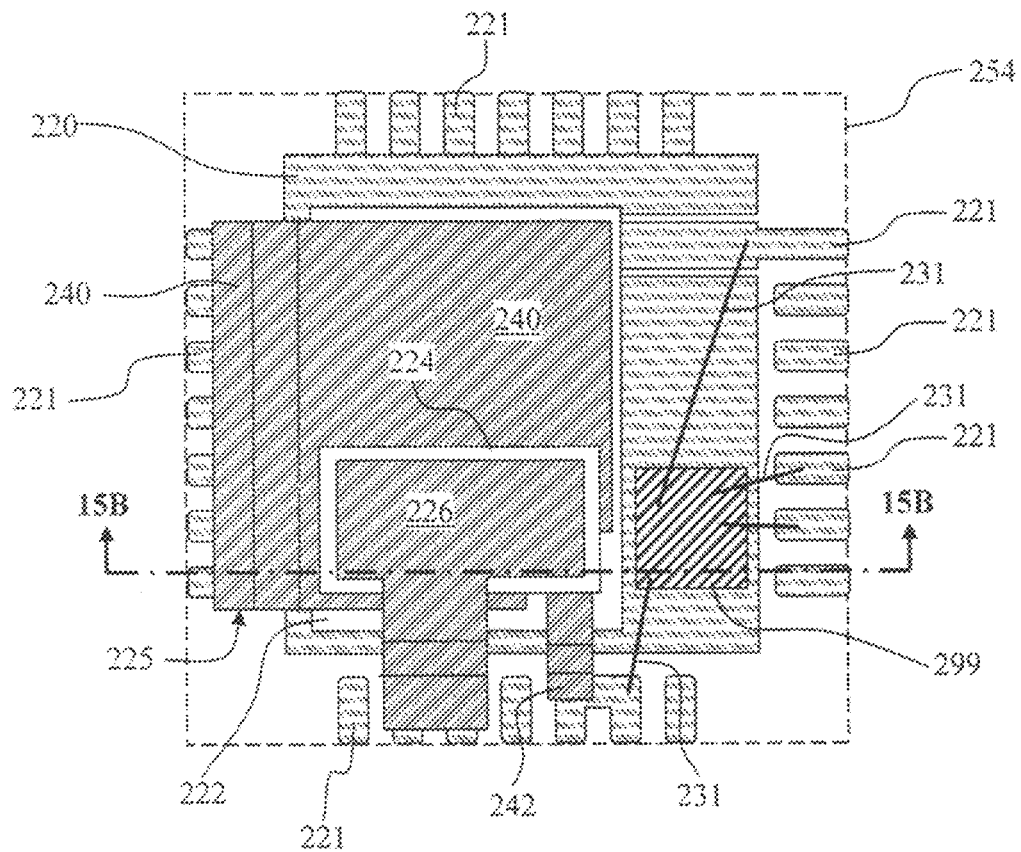


Fig. 15A

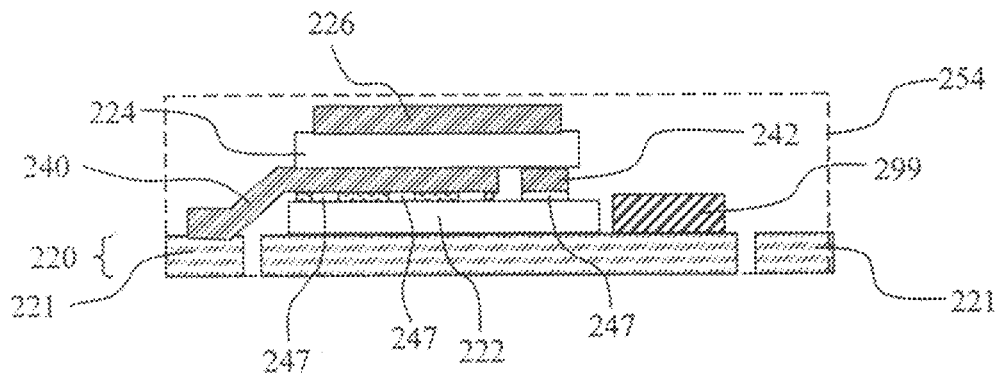


Fig. 15B

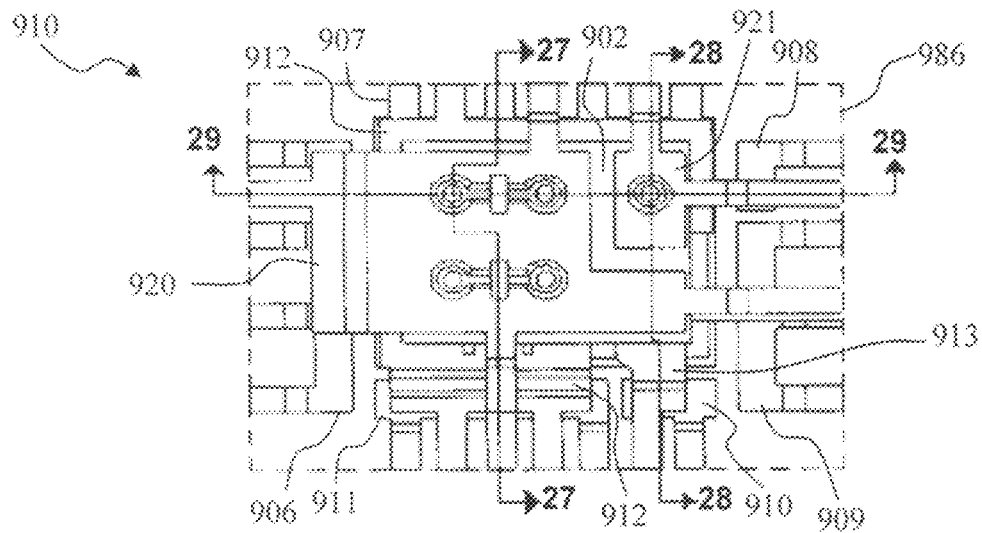


Fig. 16A

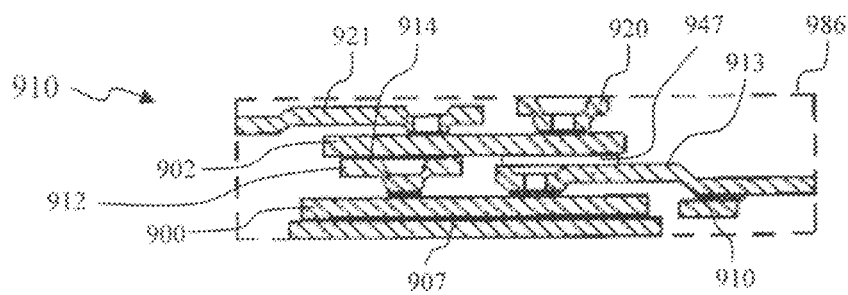


Fig. 16B

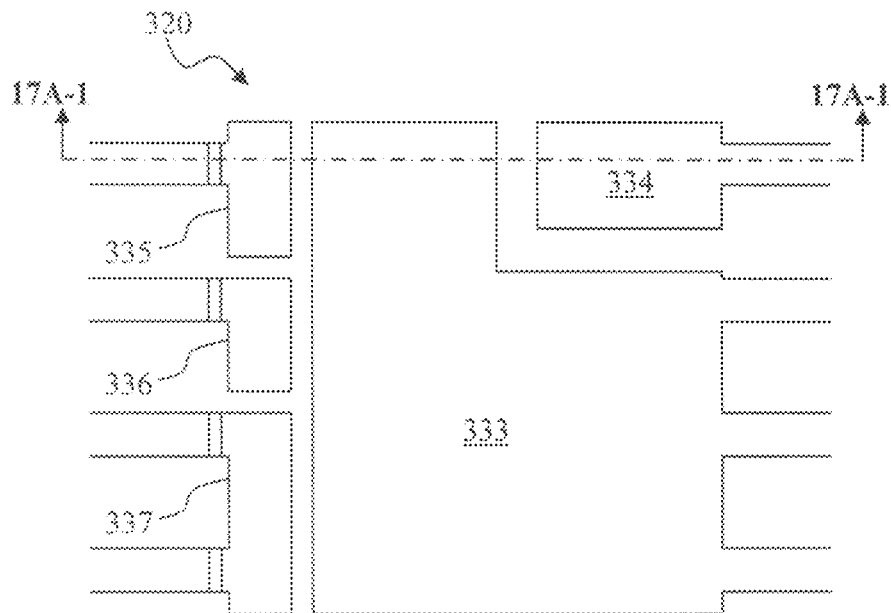


Fig. 17A



Fig. 17A-1

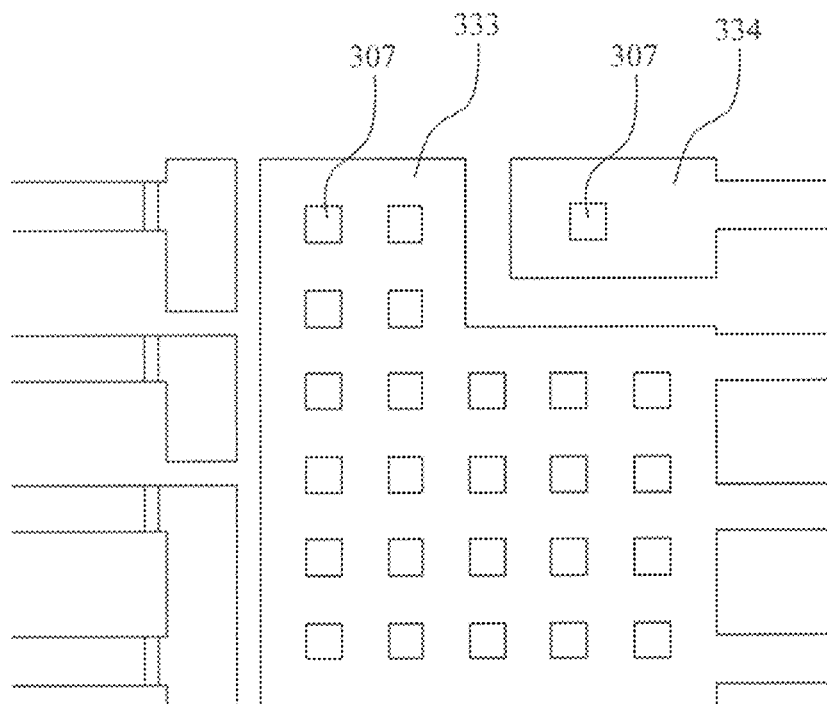


Fig. 17B

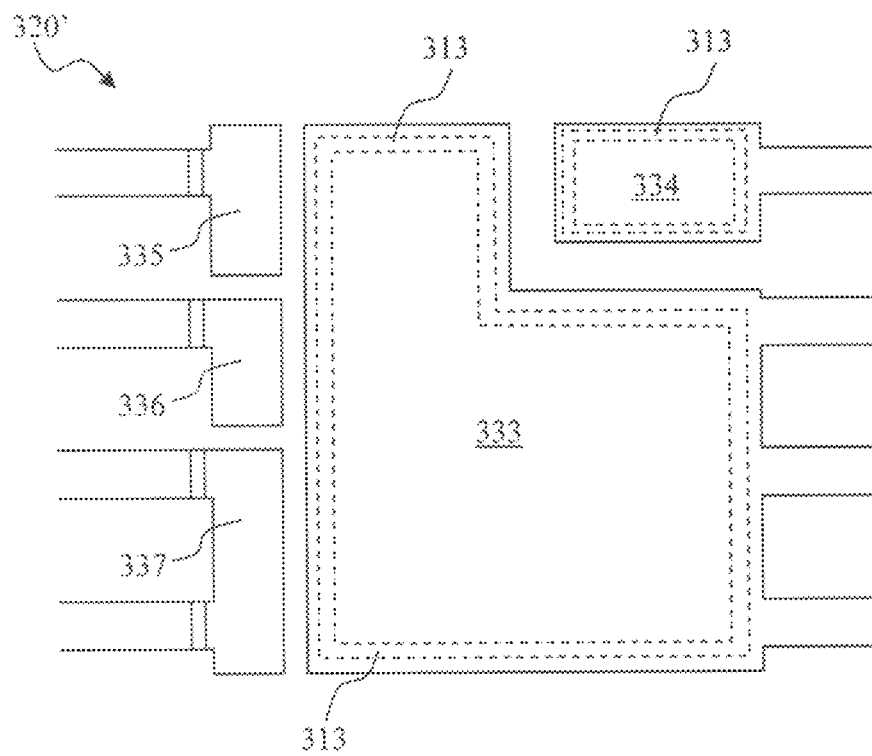


Fig. 17A'



Fig. 17A'-1

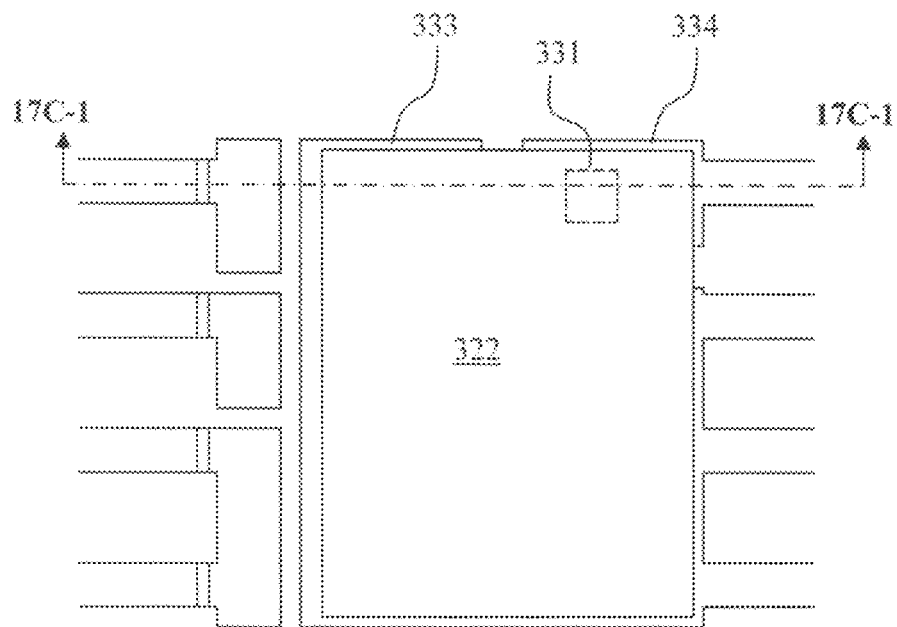


Fig. 17C

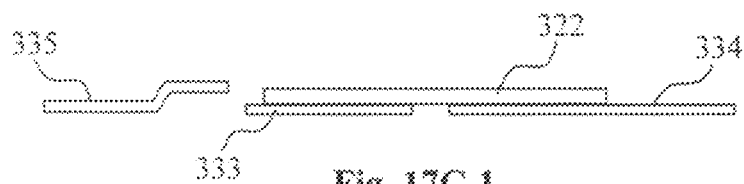


Fig. 17C-1

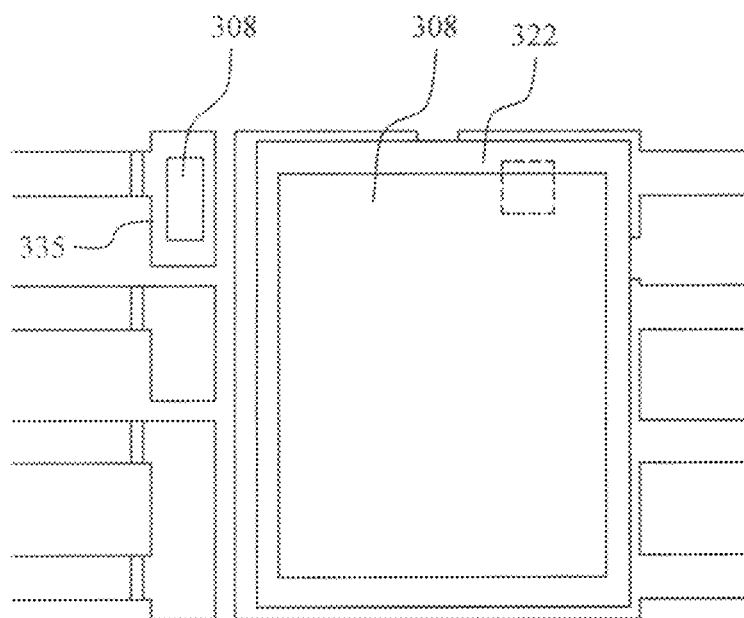


Fig. 17D

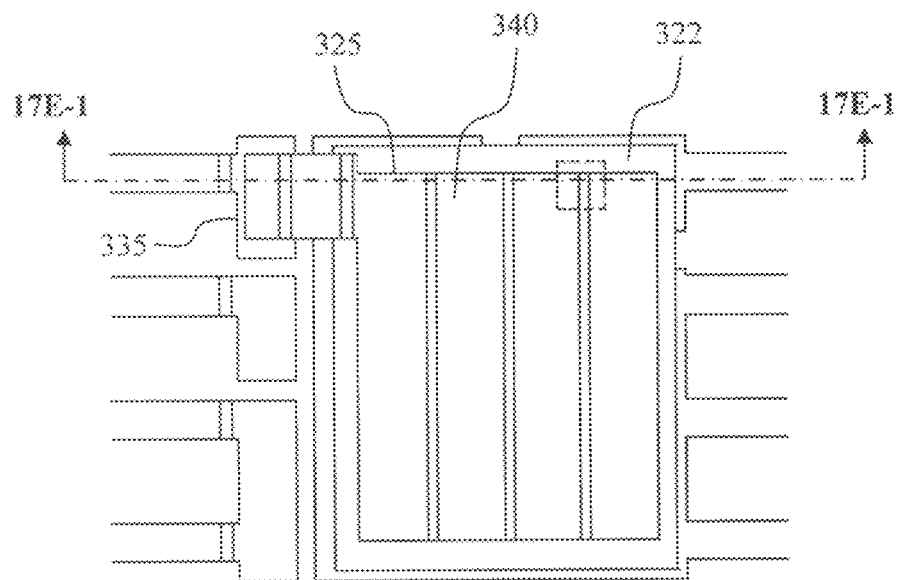


Fig. 17E

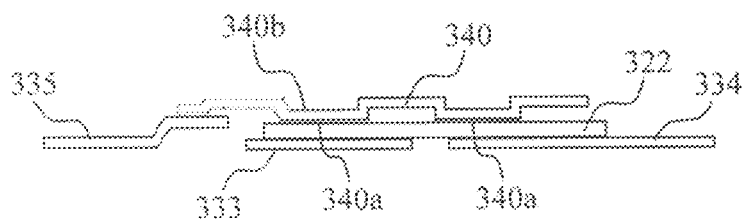


Fig. 17E-1

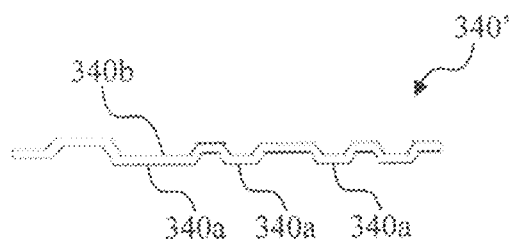


Fig. 17E-2

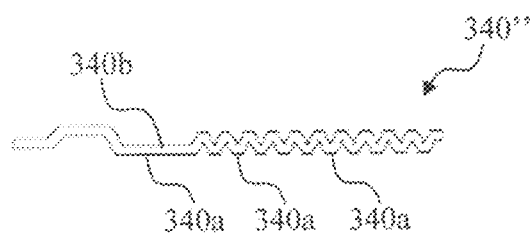


Fig. 17E-3

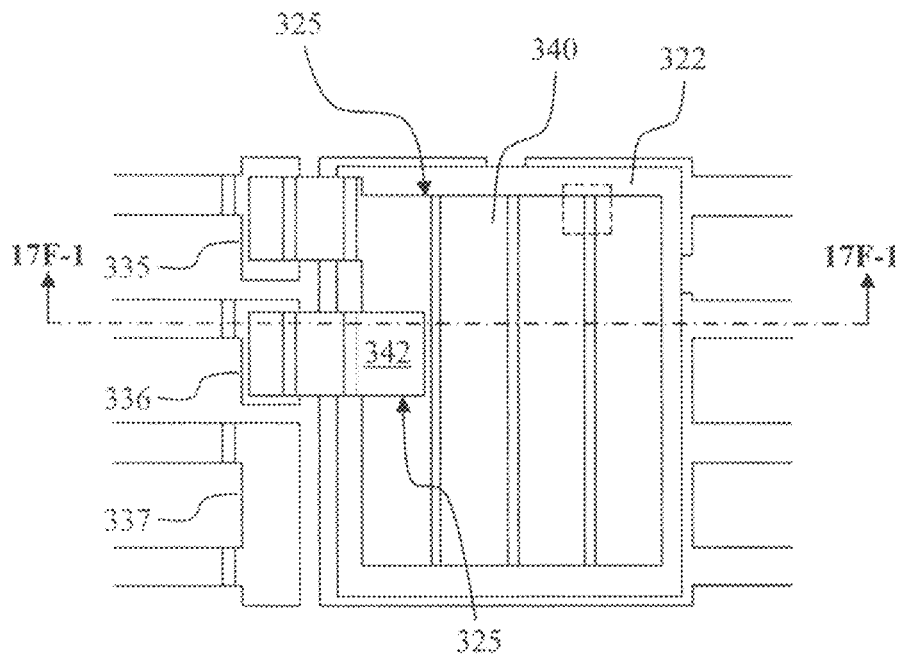


Fig. 17F

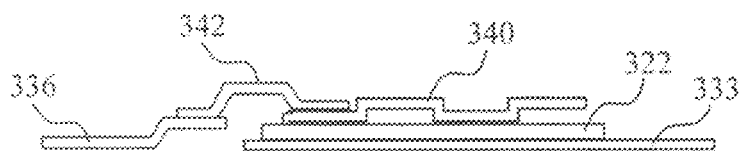


Fig. 17F-1

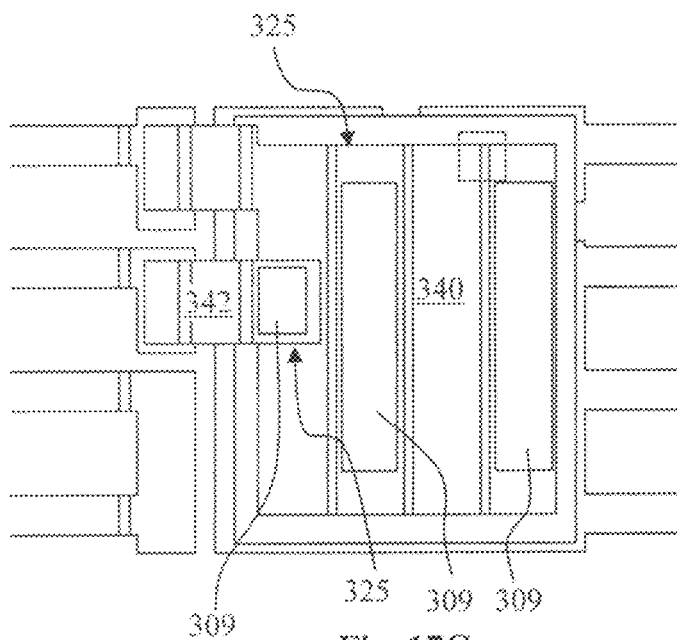


Fig. 17G

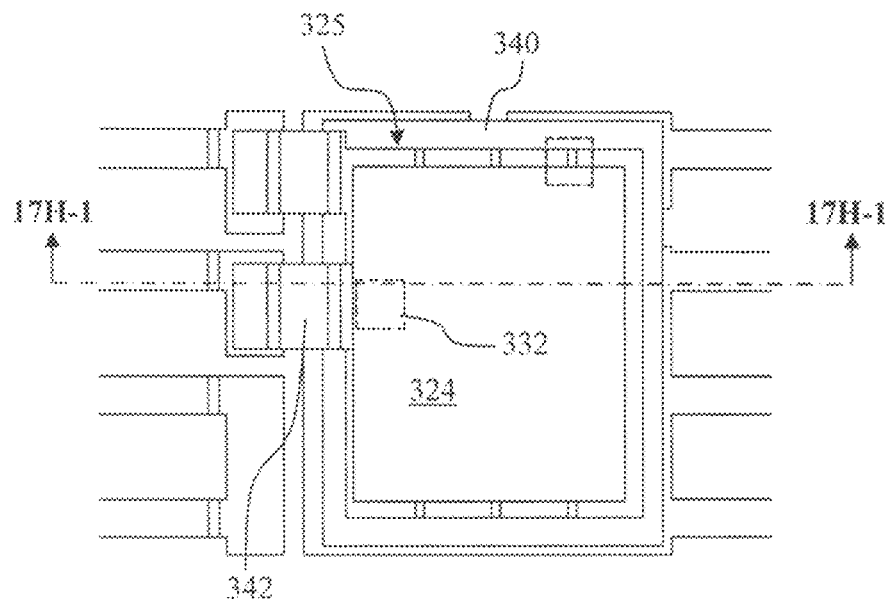


Fig. 17H



Fig. 17H-1

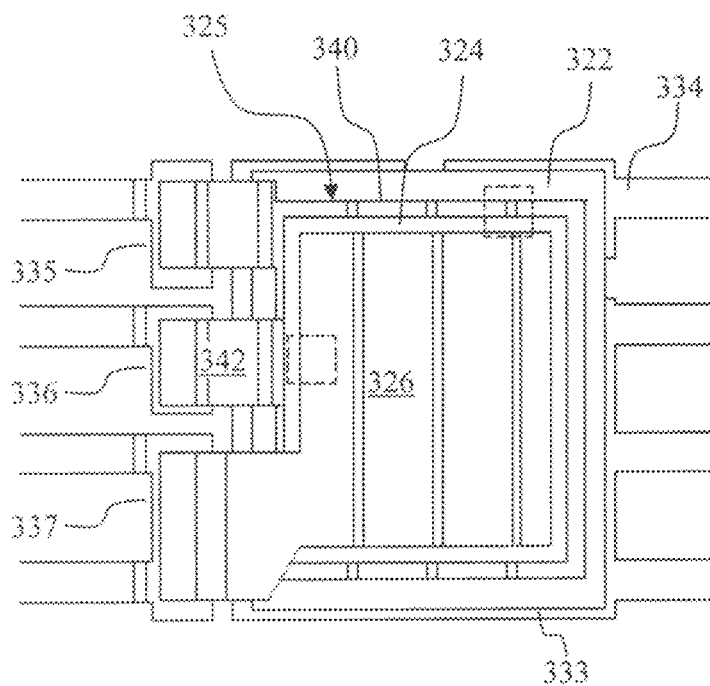


Fig. 17I



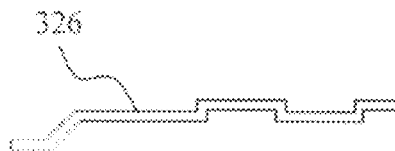


Fig. 17I-1



Fig. 17I-2

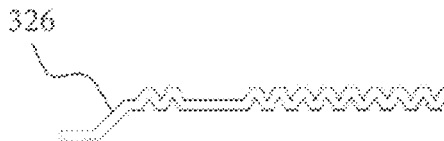


Fig. 17I-3

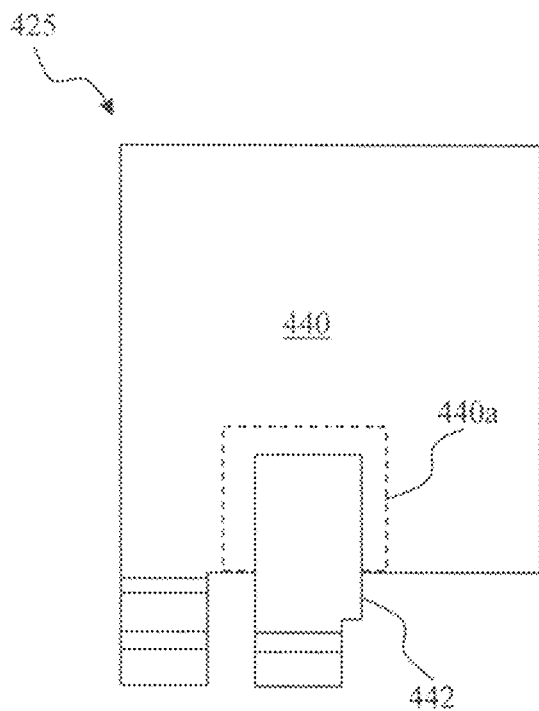


Fig. 18A

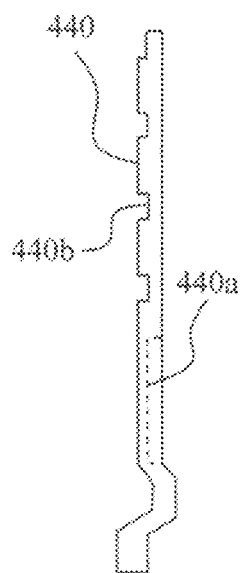


Fig. 18B



Fig. 18C

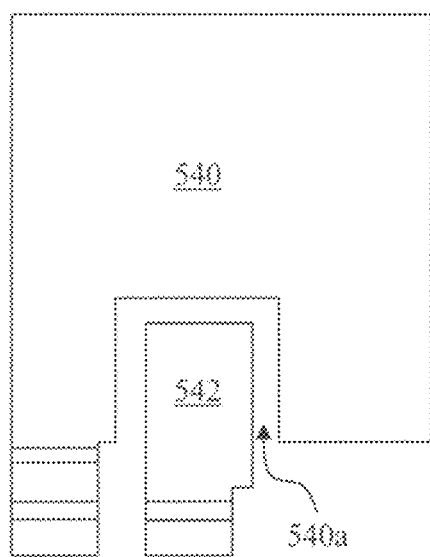


Fig. 19A

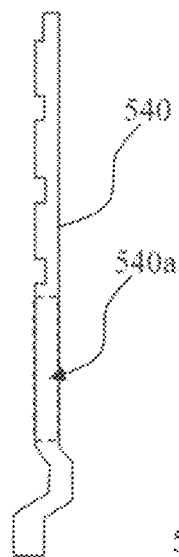


Fig. 19B

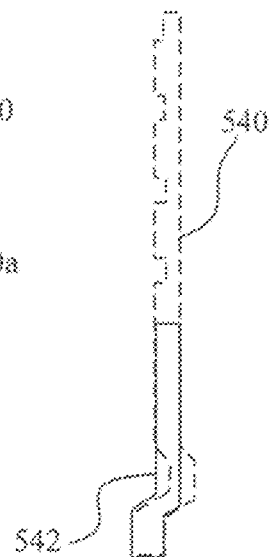


Fig. 19C

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# STACKED DUAL CHIP PACKAGE HAVING LEVELING PROJECTIONS

## CROSS-REFERENCE TO RELATED PATENT APPLICATIONS

This patent application is a Continuation Application of U.S. patent application Ser. No. 12/819,111 filed Jun. 18, 2010 entitled STACKED DUAL CHIP PACKAGE AND METHOD OF FABRICATION and having Hamza Yilmaz, Xiaotian Zhang, Yarn Xun Xue, Anup Bhalla, Jun Lu, Kai Liu, Yueh-Se Ho and John Amato listed as inventors, which is a Continuation-in-part of U.S. application Ser. No. 12/726,892 filed Mar. 18, 2010 having Jun Lu, Ming Sun, Yueh-Se Ho, Kai Liu and Lei Shi listed as inventors. This application is incorporated by reference herein.

## BACKGROUND OF THE INVENTION

The present invention generally relates to semiconductor packages and more particularly to multi-semiconductor chip packages and methods of fabrication.

In DC to DC converters, multiple field effect transistors, FETs are often electrically connected in a common package. One DC-DC converter includes a high-side (HS) FET and a low-side (LS) FET. Typically, the HS FET and LS FET are mounted side-by-side and are electrically connected employing wires. This provides a DC to DC converter with a foot print that is larger than otherwise desired.

A need exists, therefore, to form DC to DC converter packages with a size that is smaller than currently exists.

## SUMMARY OF THE INVENTION

The present invention features lead frame package having a first semiconductor die, a clip structure attached to the first semiconductor die; and a plurality of leveling projections located between the clip structure and the first semiconductor die, such that the clip structure is parallel with the semiconductor die, wherein an adhesive material is located between at least some of the leveling projections, attaching the clip structure to the first semiconductor die. These and other aspects of the invention are discussed more fully below.

## BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a perspective view of a lead frame package in accordance with a first embodiment of the present invention;

FIG. 2 is a perspective view of the lead frame package shown in FIG. 1 with encapsulating molding material removed;

FIG. 3 is a perspective view of a base lead frame and semiconductor the attached thereto that are shown in FIG. 2, with the other components of FIG. 2 being omitted;

FIG. 4 is a perspective view of a first clip structure mounted to the structure shown in FIG. 3;

FIG. 5 is bottom-up view of the clip structure shown in FIG. 4;

FIG. 6 is a partial cross sectional view of the clip structure shown in FIG. 5, taken along lines 6-6;

FIG. 7 is a perspective view showing a second semiconductor die mounted to the first clip structure shown in FIG. 4;

FIG. 8 is bottom-up view of the clip structure shown in FIG. 2;

FIG. 9 is a perspective view of the lead frame package shown in FIG. 2 in accordance with a first alternate embodiment;

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FIGS. 10A and 10B are circuit schematics showing two common half bridge circuits;

FIG. 11 is a perspective view of a lead frame package similar to that shown in FIG. 4, in accordance with a second embodiment of the present invention;

FIG. 12 is a perspective view of the lead frame package shown in FIG. 11 with a second semiconductor die mounted thereto;

FIG. 13 is a perspective view of a second clip structure mounted to the lead frame package shown in FIG. 12; and

FIG. 14 is a perspective view shown the lead frame package of FIG. 13 with encapsulating molding compound.

FIGS. 15A and 15B are a top view and a cross sectional view, respectively, of a stacked die structure of this invention co-packaged with an IC control chip.

FIGS. 16A and 16B are top and cross sectional views, respectively, based on figures from U.S. application Ser. No. 12/726,892.

FIGS. 17A through 17I-3 are top and cross sectional views showing a method of assembling a stacked die structure according to an alternative embodiment of this invention.

FIGS. 18A through 18C are top and cross sectional views of a stacked die structure according to another alternative embodiment of this invention.

FIGS. 19A through 19C are top and cross sectional views of a stacked die structure according to another alternative embodiment of this invention.

## DETAILED DESCRIPTION OF THE INVENTION

Referring to both FIGS. 1 and 2, a lead frame package 10 includes a plurality of leads 11-18, base lead frame 20, first and second semiconductor dies 22 and 24 and first and second Clip structures 25 and 26. First clip structure 25 is positioned between first and second semiconductor dies 22 and 24. First semiconductor die 22 is positioned between base lead frame 20 and first clip structure 25. Second semiconductor die 24 is positioned between first and second clip structures 25 and 26. Semiconductor dies 22 and 24 may be any known in the electrical art. In the present example semiconductor dies 22 and 24 are transistors such as a power Field Effect Transistor (FET) or a power metal oxide semiconductor FET (MOS-FET).

Referring to both FIGS. 2 and 3, semiconductor die 22 has a source contact 30, a gate contact 31 and a drain contact 32. Source contact 30 and gate contact 31 are on a common side of semiconductor die 22 disposed opposite to drain contact 32. As a result, source contact 30 is shown in dashed lines. Specifically, source and gate contacts 30 and 31 face base lead frame 20 and are in electrical communication therewith. First semiconductor die 22 has an area that is in superimposition with first clip structure 25.

Base lead frame 20 includes first and second 33 and 34 electrically conductive segments, which may be formed from any suitable conductive material, such as gold, copper and aluminum or an alloy thereof. First segment 33 is electrically isolated from second segment 34. The relative dimensions of first and second segments 33 and 34 are established to satisfy the operational and electrical requirements of first semiconductor die 22. To that end, first segment 33 is in superimposition and connected with source contacts 30, and second segment 34 is in superimposition and connected with gate contact 31 of the first semiconductor die 22. Since the source and gate contacts are typically found on the front side of a vertical MOSFET die, the first semiconductor die 22 can be said to be flip chip mounted on the base lead frame, with the drain contact 32 sticking up.

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Referring to FIGS. 2, 3 and 4, a clip structure 25 is attached to drain contact 32 of first semiconductor die 22. Specifically, clip structure 25 includes multiple spaced-apart conductive segments 40 and 42. Conductive segment 40 is electrically isolated from segment 42 using any technique known. As shown, a void 44 is present between conductive segments 40 and 42. Conductive segment 40 is in electrical communication with drain contact 32 and may be attached thereto using any known technique, e.g., conductive epoxy. Conductive segment 42 may be attached to semiconductor die 22 non-conductively, e.g. with non-conductive epoxy, so as to be isolated from drain contact 32.

Referring to both 5 and 6, extending from a side of first clip structure 25 facing first semiconductor die 22 are one or more electrically insulative projections 47 which may be formed from silicone. The projections are attached to the clip structure 25 using a known technique before attaching clip structure 25 to first semiconductor die 22 in one example, projections 47 are arranged to extend from segments 40 and 42 toward first semiconductor die 22 and being attached thereto using any suitable adhesive. As a result, a hiatus 49 is present between first semiconductor die 22 and first clip structure 25 as can be seen in the cross section of FIG. 6, taken along lines 6-6 of FIG. 5. Conductive adhesive, such as solder or conductive epoxy may be used to fill in the hiatus 49 and electrically connect segment 40 to first semiconductor die 22. Projections 47 are included to ensure that first clip structure 25 is substantially level during fabrication of package 10. As a result, all projections 47 may have a common height. Alternatively, the height of projections may be tailored to compensate for non-homogeneities of the thickness or contours of first clip structure 25 so as to maintain a substantially level surface upon which to mount second semiconductor die 24. The projections 47 also help to keep insulate the segment 42 from first semiconductor die 22.

Referring to both FIGS. 4 and 7, attached upon clip structure 25 is second semiconductor die 24. Semiconductor die 24 includes gate, source and drain contacts 46, 48 and 50. Although drain contact 50 is shown as being a portion of the backside of semiconductor die 24 in practice the drain contact may comprise the entire backside. Gate contact 46 faces, and is in superimposition with, conductive segment 42 being in electrical communication therewith using, e.g., conductive epoxy or solder. Source contact 48 faces conductive segment 40 and is in electrical communication therewith using, e.g., conductive epoxy or solder. Drain contact 50 is disposed on a side of semiconductor die 24 facing away from clip structure 25. Since the gate and source contacts 46, 48 are facing down, second semiconductor die 24 can be said to be mounted flip chip on first clip structure 25. Note that the projections 47 allow the segment 42 of first clip structure 25 be located over first semiconductor die 22 while being electrically isolated from it—thus the gate contact 46 of second semiconductor die 24 can be electrically connected to conductive segment 42 without being electrically connected to the first semiconductor die 22. In addition the projections 47 ensure that the second semiconductor die 24 has an even surface on segments 40 and 42 to which to be mounted.

Referring to FIGS. 2, 7 and 8 second clip structure 26 is attached to drain contact 50 e.g., using conductive epoxy or solder. Second clip structure 26 may also include a plurality of leveling projections 51, shown in FIG. 8, extending toward second semiconductor die 24 in a manner discussed above with respect to first clip structure 25, shown in FIGS. 5 and 6. These projections may help keep the second clip structure 26 level throughout the assembly process and can be conductive or non-conductive. A conductive adhesive (e.g. conductive

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epoxy or solder) may be used to attach and electrically connect second clip structure 26 to the second semiconductor die 24. This stack may then be wholly or partially encapsulated using any suitable molding compound 52, shown FIG. 1. As shown molding compound 52 completely encapsulates semiconductor dies 22 and 24, with parts of leads 11-18 being exposed.

As shown each of leads 11-18 are integrally formed with one of base lead frame 20, first clip structure 25 or second clip structure 26. As shown, leads 12, 17 and 18 are integrally formed with base lead frame 20 and leads 11, 13 and 14 are integrally formed with first clip structure 25. Leads 15 and 16 are integrally formed with second clip structure 26. As a result, leads 12 and 17 function as a pin out of lead frame package 10 for source contact 30 of first semiconductor die 22. Lead 18 function as the pin outs for gate contact 31, respectively, of first semiconductor die 22. Lead 11 functions as the pin outs for gate contact 46 of second semiconductor die 24, and leads 13 and 14 function as the pin outs for both source contact 48 of second semiconductor die 24 and drain contact 32 of first semiconductor die 22. Leads 15 and 16 function as pin outs for drain contact 50 of second semiconductor die 24.

Although the leads 11-18 are shown as being integral with one of base lead frame 20, first clip structure 25 or second clip structure 26, this is not necessary. For example, any one of leads 11-18 may be placed in electrical contact with one of base lead frame 20, first clip structure 25 or second clip structure 26 using any known techniques, such as use of a wire bond or conductive ribbon 54, shown in FIG. 9, which is associated with wire bonding or ribbon bonding techniques. In these cases, the second clip structure 26 is not necessary and the drain contact 50 of second semiconductor die 24 may be bonded directly to leads 15 and 16 using either wire bonding or ribbon bonding techniques. Also, instead of the leads being integrally formed with the first and second clip structures, the first and second clip structures can alternatively make contact to leads of a base lead frame.

FIG. 10A shows a half bridge circuit of two transistors in series. More specifically, FIG. 10A shows two n-channel MOSFETs in series, with the drain of low side MOSFET 80 connected to the source of high side MOSFET 90. This circuit configuration is particularly useful in power conversion systems. Typically, the low side MOSFET 80 handles more current than the high side MOSFET 90. Thus it typically requires a larger die size than the high side MOSFET 90. In addition, a typical vertical MOSFET is constructed with the source and gate contacts on the top side, and the drain contact on the bottom side. Taken together, this presents a problem for stacking MOSFETs for a half bridge circuit. For geometric, and stability reasons, the larger die, e.g., the low side MOSFET, should go on the bottom. Thus first semiconductor die (of FIG. 2) is the low side MOSFET 80, and second semiconductor die 24 is the high side MOSFET 90. However, to effect the necessary connections of the drain of low side to source of high side, both MOSFETs must be mounted flip chip style. However, now it is difficult to make a connection to the gate of the high side MOSFET, since the gate contact is facing down toward the low side MOSFET. This invention solves this by using a non-conductive projection 47 on the bottom of the conductive segment 42 of first clip structure 25. This way, a connection can be made to gate contact 46 of second semiconductor die 24, without shorting it the first semiconductor die 22.

In an alternative circuit shown in FIG. 10B, two MOSFETs are attached in series, however in this case, the low side MOSFET 85 is an n-channel MOSFET, while the high side

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MOSFET **95** is a p-channel MOSFET. In this configuration the drain of the high side MOSFET **95** is connected to the drain of the low side MOSFET **85**, which allows a simpler stacking configuration as will be illustrated in FIGS. **11** to **14**.

Referring to FIGS. **11** and **12**, in accordance with another embodiment and the circuit of FIG. **10B**, a first semiconductor die **122** is flip chip mounted on a base lead frame **120**, similarly to FIG. **3**. A first clip structure **125** is attached to the drain of the first semiconductor die **122**; however in this case the first clip structure **125** consists of only one conductive segment. The second semiconductor die **124** is mounted so that gate contact **146** and source contact **148** faces away from first semiconductor die **122**. Drain contact **150** of second semiconductor die **124** faces first clip structure **125**. Unlike first clip structure **25**, first clip structure **125** is of unitary construction in that is comprised of a single conductive element, with drain contacts **150** of second semiconductor die **124** and drain contact of first semiconductor die **122** being in electrical communication therewith.

Gate and source contacts **146** and **148** are placed in electrical communication with a second clip structure **126**. Similar to first clip structure **25**, second clip structure **126** includes multiple spaced-apart conductive segments **140** and **142**. Conductive segment **140** is in electrical communication with source contact **148** and is electrically isolated from segment **142** using any technique known. As shown, a void **144** is present between conductive segments **140** and **142**. Conductive segment **140** is in electrical communication with gate contact **146** and may be attached thereto using any known technique, e.g., conductive epoxy. This stack may then be partially or wholly encapsulated in a molding compound **152**, shown in FIG. **14**.

As shown, leads **112**, **117** and **118** are integrally formed with base lead frame **120**, and leads **113** and **114** are integrally formed with first clip structure **125**. Leads **111**, **115** and **116** are integrally formed with second clip structure **126**. As a result, leads **112** and **117** function as pin outs of lead frame package **110** for the source contact of first semiconductor die **122**. Lead **118** functions as the pin out for the gate contact of first semiconductor die **122**. Leads **113** and **114** functions as the pin outs for both drain contacts **150** of second semiconductor die **124** and the drain contacts of first semiconductor die **122**. Leads **115** and **116** function as pin outs for source contact **148** of second semiconductor die **124**, and lead **111** functions as the pin outs for gate contact **146** of the same. In this case, the first semiconductor die **122** is the low side n-channel MOSFET **85** (of FIG. **10B**), and second semiconductor die **124** is the high side p-channel MOSFET **95**.

Although the leads **111-118** are shown being integral with one of base lead frame **120**, first clip structure **125** or second clip structure **126**, this is not necessary. For example, any one of leads **111-118** may be integrally formed on a segment of base lead frame, with the first clip structure **125** or second clip structure **126** making contact to it using any known techniques, as discussed above. Also, the second clip structure could be replaced with bond wires or conductive ribbons, as discussed above.

The die stack structures like those shown above can also be co-packaged with a control integrated circuit (IC) chip to form an integrated power IC package as shown in FIGS. **15A** and **15B**. FIG. **15B** is taken along a cross section line **15B** of FIG. **15A**. A base lead frame **220**, e.g. for a 5x5 QFN (quad flat non-leaded) package, for this package may include a plurality of leads **221**. In this case, the base lead frame **220** may have leads **221** extending both ways in two orthogonal directions. A first semiconductor die **222** may be flip chip mounted on the base lead frame **220** as described above. A

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first clip structure **225**, comprising conductive segments **240** and **242** may be attached over the first semiconductor die **222**. Non conductive projections **247** may be first formed on the bottom of first clip structure **225** to ensure even placement, and to keep segment **242** from being electrically connected to first semiconductor die **222**, as described above. Conductive adhesive between projections **247** may conductively attach the segment **240** to the first semiconductor die. A second semiconductor die **224** can be mounted on segments **240** and **242** of the first clip structure. A second clip structure **226** may be placed over the second semiconductor die **224**. As shown in the figure, the first and second clip structures **225** and **226** do not have leads integrally formed within themselves, but instead are connected to other structures on which the leads **221** are formed. A controller IC chip **299** is co-packaged on the base lead frame **220** next to the stacked semiconductor dies **222** and **224**. The controller IC chip **299** may be non-conductively mounted on base lead frame **220**, e.g. by non-conductive epoxy. Thus an integrated power IC package may be formed. The outline of the chip package is shown by dashed line **254**. Bond wires **231** may connect the IC chip **299** to various leads **221** and to the gates of semiconductor dies **222** and **224** through leads **221**, to effect control of the semiconductor dies. For example, the IC chip **299** may be a power IC control chip, and the first and second semiconductor dies **222** and **224** may be low side and high side field effect transistors (FETs), respectively, to form an integrated power IC package.

These non-conductive projections can also be used in an extension to U.S. application Ser. No. 12/726,892 filed Mar. 18, 2010. In FIGS. **16A** and **16B**, which are adapted from FIGS. **26** and **28** of U.S. application Ser. No. 12/726,892, a stacked die semiconductor package **910** is shown. FIG. **16B** is taken along cross section **28-28** of FIG. **16A**. A base lead frame including conductive segments **906**, **907**, **908**, **909**, **910**, and **911**, is found at the bottom. A first semiconductor die **900** is mounted on the segment **907** of the base lead frame. As shown here, the semiconductor is mounted device side up, i.e. not flip chip mounted. A first clip structure including conductive segments **912** and **913** are placed on the first semiconductor die **900**. A second semiconductor die **902** may be placed over the first clip structure segments **912** and **913**. A single non-conductive projection **947** may be placed over the clip structure segment **913** to prevent electrical connection to the second semiconductor die **902**. Second semiconductor die **902** is also mounted device side up. Finally, the second clip structure including conductive segments **920** and **921** may be placed on the second semiconductor die **902**. The package **910** may be encased in molding compound **986**.

In this case the first semiconductor die **900** is the high side MOSFET **80** (FIG. **10A**), and the second semiconductor die **902** is the low side MOSFET **90** and have source and gate contacts (not shown) facing up and drain contact (not shown) facing down. In this case, the low side MOSFET die **902** is stacked over the high side MOSFET die **900**, but can at least be made as large as the high side MOSFET die **900**. The low side MOSFET die **902** can overlap the gate contact (not shown) portion of the high side MOSFET die **900** because the high side gate clip **913** is not electrically connected to the low side MOSFET die **902**. The non-conductive projection **947** can help ensure that no electrical connection is made between the two and keep the second semiconductor die **902** level and secure when mounted on the first clip structure segments **912** and **913**.

The stacked die structure can also be realized in an alternative configuration where the first clip structure comprises two overlapping segments. Referring to FIGS. **17A-17C**, a

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first semiconductor die 322 is flip chip mounted on a base lead frame 320 including conductive segments 333, 334, in a manner similar to that described above. FIG. 17A shows a top view of the base lead frame 320. The base lead frame 320 may also include conductive lead segments 335, 330 and 337. In the cross sectional view of FIG. 17A-1 which is taken along line 17A-1 of FIG. 17A, the lead segments (e.g. 335) are shown to have raised ends. By way of example, a conductive adhesive 307 may first be applied onto the conductive segments 333 and 334 (FIG. 17B) before attaching first semiconductor die 322. Optionally, as shown in FIG. 17A', the base lead frame 320' may include a groove 313 on its top surface that runs near its edge. The groove 313 can be used to contain the conductive adhesive, e.g. solder, during the attachment process. FIG. 17A'-1 shows a cross sectional view of a groove 313. Semiconductor die 322 is conductively attached to base lead frame segments 333 and 334. The gate contact 331 of die 322 is facing down, but its relative location is indicated by dashed lines in FIG. 17C. The gate contact 331 contacts the conductive segment 334, while the source contact (not shown) contacts the conductive segment 333 of base lead frame 320. FIG. 17C-1 is a cross sectional view of FIG. 17C along line 17C-1 and shows the semiconductor die 322 mounted atop base lead frame segments 333 and 334. By way of example, the top of the raised portion of lead frame segment 335 may be co-planar with the top of semiconductor die 322.

Referring to FIGS. 17D-17F, conductive adhesive 308 may be placed on the first semiconductor die 322 and on lead segment 335 of the base lead frame 320. A first segment 340 of a first clip structure 325 is attached on the first semiconductor die 322. One end of the first segment 340 is also attached to a lead segment 335 of the base lead frame. A second segment 342 of the first clip structure 325 is non-conductively attached on the first segment 340, e.g. with non-conductive epoxy; the second segment 342 is also connected to a lead segment 336 of the base lead frame at another end. Optionally, a non-conductive projection (not shown) may be used to help ensure the proper spacing and non-conduction between first segment 340 and second segment 342. The first segment 340 may include a zig-zag shaped structure as shown in the cross sectional FIG. 17E-1, taken along cross section line 17E-1. The zig-zag shape has elasticity and reduced fixed contact area to provide stress release from stresses developed at the die/clip interface. The zig-zag structure also allows for outgassing from the conductive adhesive which can reduce void formation and improve electrical performance and reliability. The zig-zag pattern may include a series of lowered bottom surfaces 340a at which the clip first segment 340 attaches to the first semiconductor die 322. The top of first segment 340 should include a recessed portion 340b to which the second segment 342 can attach. This allows the top of second segment 342 and the upper portions of first segment 340 to be co-planar, as seen in the cross section of FIG. 17F-1, taken along line 17F-1 of FIG. 17F. The recessed portion 340b may be formed, e.g., by stamping, bending, or etching. FIGS. 17E-2 and 17E-3 show alternative shapes for first clip structure first segments 340' and 340". Due to the recessed portion 340b, the top of second segment 342 may be coplanar with the top of first segment 340.

Next conductive adhesive 309 can be deposited on top of first segment 340 and second segment 342 of first clip structure 325 as shown in FIG. 17G, and the second semiconductor die 324 can be flip chip mounted over the first and second segments 340 and 342 of the first clip structure 325 as shown in FIG. 17H. The location of the gate contact 332 of the

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second semiconductor die 324, though facing down, is indicated by dashed lines and contacts the second segment 342 of the first clip structure 325. The source of second semiconductor die 324 also faces down and contacts the first segment 340 of first clip structure 325. FIG. 17H-1 is a cross section taken along line 17H-1 of FIG. 17H. As can be seen, the lower portions of segment 340 contact the first semiconductor die 322, and the higher portions of segment 340 contact the second semiconductor die 324. The second segment 342 is non-conductively attached to a recessed portion of first segment 340. The tops of first and second segments 340 and 342 can thus be coplanar to allow for stacking the second semiconductor die 324 atop thereof, while also allowing for connection to be made from the second semiconductor die gate contact 332. A second clip structure 326 may be mounted over the second semiconductor die 324 and also connected to a lead segment 337. FIGS. 17I-1 through 17I-3 are side views of some possible shapes of the second clip structure 326. By way of example the first semiconductor die 322 may be a low side FET 80 (of FIG. 10A) and second semiconductor die 324 may be a high side FET 90.

In one embodiment, the first segment 340 may be bent or stamped into shape to form the recessed region to which the second segment 342 can attach. In an alternative embodiment, as shown in FIGS. 18A through 18C, the first segment 440 of first clip structure 425 may have a half etched portion 440a to form the recessed portion for the second segment 442 to attach to. In the side view of first segment 440 in FIG. 18B, the location of the recessed portion 440a is indicated by dashed lines. In the side view of the second segment 442 shown in FIG. 18C, the outline of the first segment 440 is shown in dashed lines. The first segment 440 can also have the zig-zag structure formed by a half-etch process, forming thinned portions 440b interspersed along the bottom of the first segment 440.

In another alternative embodiment, as shown in FIGS. 19A to 19C, a portion 540a of the first segment 540 may be entirely removed such that the second segment 542 may be located there—the second segment 542 may then be non-conductively attached to first semiconductor die 322, similarly to FIG. 4.

It should be understood that the foregoing description is merely an example of the invention and that modifications and may be made thereto without departing from the spirit and scope of the invention and should not be construed as limiting the scope of the invention. The scope of the invention, therefore, should be determined with respect to the appended claims, including the full scope of equivalents thereof.

The invention claimed is:

1. A semiconductor package comprising:

a first semiconductor die;  
a clip structure attached to the first semiconductor die; and  
a plurality of leveling projections located between the clip structure and the first semiconductor die, such that the clip structure is parallel with the semiconductor die, wherein an adhesive material is located between at least some of the leveling projections, attaching the clip structure to the first semiconductor die, at least some of said adhesive material being electrically conductive and located between at least some of the leveling projections, electrically connecting at least a portion of the clip structure to the first semiconductor die, with the clip structure further comprising a first conductive segment and a second conductive segment, the first conductive segment being conductively attached to the first semi-

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conductor die, and the second conductive segment being in superimposition with and electrically isolated from the first semiconductor die.

2. The package of claim 1 wherein said leveling projections have a common height.

3. The package of claim 1 wherein said clip structure is in electrical communication with a package lead.

4. The package of claim 1 wherein the clip structure further comprises a first conductive segment and a second conductive segment.

5. The package of claim 4 wherein the tops of the first and second conductive segments are co-planar.

6. The package of claim 1 further comprising a second semiconductor chip stacked on the clip structure on a side opposite that of the first semiconductor die.

7. A semiconductor package comprising:

a first semiconductor die;

a clip structure, having first and second conductive segments, attached to the first semiconductor die; and

a plurality of electrically non-conductive leveling projections located between the clip structure and the first semiconductor die, such that the clip structure is parallel with the semiconductor die, wherein an adhesive material is located between at least some of the leveling projections, attaching the clip structure to the first semiconductor die, with the first conductive segment being conductively attached to the first semiconductor die, and the second conductive segment being superimposed with but electrically isolated from the first semiconductor die.

8. The package of claim 7 wherein said leveling projections have a common height.

9. The package of claim 7 wherein said clip structure is in electrical communication with a package lead.

10. The package of claim 7 wherein a sub-portion of said adhesive material is electrically conductive and located

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between at least some of the leveling projections, electrically connecting at least a portion of the clip structure to the first semiconductor die.

11. The package of claim 7 wherein the tops of the first and second conductive segments are co-planar.

12. The package of claim 7 further comprising a second semiconductor chip stacked on the clip structure on a side opposite that of the first semiconductor die.

13. A semiconductor package comprising:

a first semiconductor die;

a clip structure, having first and second conductive segments, attached to the first semiconductor die;

a plurality of electrically non-conductive leveling projections located between the clip structure and the first semiconductor die, such that the clip structure is parallel with the semiconductor die, wherein an adhesive material is located between at least some of the leveling projections, attaching the clip structure to the first semiconductor die, with the first conductive segment being electrically conductively attached to the first semiconductor die, and the second conductive segment is superimposed with and electrically isolated from the first semiconductor die; and

a second semiconductor chip stacked on the clip structure on a side opposite that of the first semiconductor die.

14. The package of claim 13 wherein said leveling projections have a common height.

15. The package of claim 13 wherein said clip structure is in electrical communication with a package lead.

16. The package of claim 13 wherein a sub-portion of said adhesive material is electrically conductive and located between at least some of the leveling projections, electrically connecting at least a portion of the clip structure to the first semiconductor die.

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